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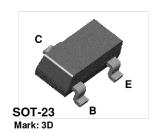
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# MPSH81



# MMBTH81



## **PNP RF Transistor**

This device is designed for general RF amplifier and mixer applications to 250 mHz with collector currents in the 1.0 mA  $\,$ to 30 mA range. Sourced from Process 75.

## **Absolute Maximum Ratings\***

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	20	V
V <sub>CBO</sub>	Collector-Base Voltage	20	V
V <sub>EBO</sub>	Emitter-Base Voltage	3.0	V
I <sub>C</sub>	Collector Current - Continuous	50	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

 $<sup>^{\</sup>star}$ These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
  3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

## Thermal Characteristics TA = 25°C unless otherwise noted

Symbol	Characteristic	М	Units	
		MPSH81	*MMBTH81	
P <sub>D</sub>	Total Device Dissipation	350	225	mW
	Derate above 25°C	2.8	1.8	mW/℃
R <sub>euc</sub>	Thermal Resistance, Junction to Case	125		°C/W
R <sub>eJA</sub>	Thermal Resistance, Junction to Ambient	357	556	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

#### **PNP RF Transistor**

(continued)

#### **Electrical Characteristics**

TA = 25°C unless otherwise noted

Symbol	Parameter	Parameter Test Conditions				
OFF CHAP	RACTERISTICS					
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage*	$I_{\rm C} = 1.0 \text{ mA}, I_{\rm B} = 0$	20		V	
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_{\rm C} = 10 \ \mu {\rm A}, \ I_{\rm E} = 0$	20		V	
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10 \mu A, I_C = 0$	3.0		V	
I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0		100	nA	
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 2.0 \text{ V}, I_{C} = 0$		100	nA	

#### **ON CHARACTERISTICS**

h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> = 5.0 mA, V <sub>CE</sub> = 10 V	60		
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_{\rm C} = 5.0 \text{ mA}, I_{\rm B} = 0.5 \text{ mA}$		0.5	V
V <sub>BE(on)</sub>	Base-Emitter On Voltage	$I_C = 5.0 \text{ mA}, V_{CE} = 10 \text{ V}$		0.9	V

#### SMALL SIGNAL CHARACTERISTICS

f <sub>T</sub>	Current Gain - Bandwidth Product	$I_{\rm C} = 5.0 \text{ mA}, V_{\rm CE} = 10 \text{ V},$	600		MHz
		f = 100 MHz			
C <sub>cb</sub>	Collector-Base Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1.0 \text{ MHz}$		0.85	pF
C <sub>ce</sub>	Collector Emitter Capcitance	V <sub>CB</sub> = 10 V, I <sub>B</sub> = 0, f = 1.0 MHz		0.65	pF

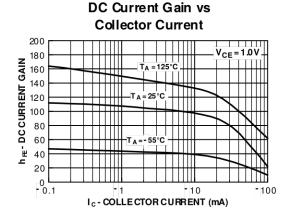
<sup>\*</sup>Pulse Test: Pulse Width ≤300 μs, Duty Cycle ≤2.0%

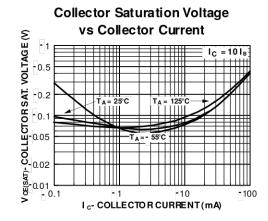
NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

### **Spice Model**

PNP(Is=10f Xti=3 Eg=1.11 Vaf=100 Bf=133.8 Ise=1.678p Ne=2.159 Ikf=.1658 Nk=.901 Xtb=1.5 Var=100 Br=1 Isc=9.519n Nc=3.88 Ikr=5.813 Rc=7.838 Cjc=2.81p Mjc=.1615 Vjc=.8282 Fc=.5 Cje=2.695p Mje=.3214 Vje=.7026 Tr=11.32n Tf=97.83p Itf=69.29 Xtf=599u Vtf=10)

## **Typical Characteristics**

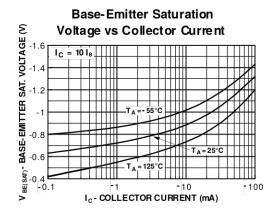


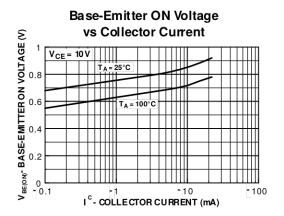


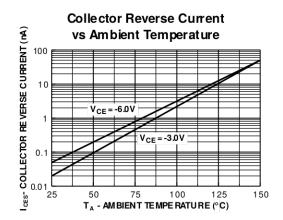
#### **PNP RF Transistor**

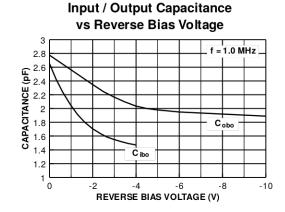
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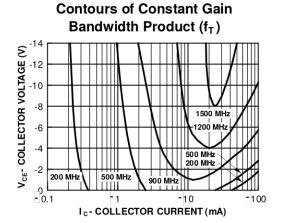
# Typical Characteristics (continued)

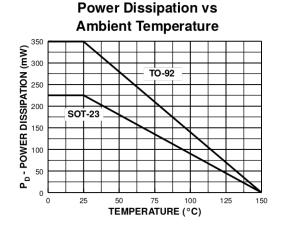


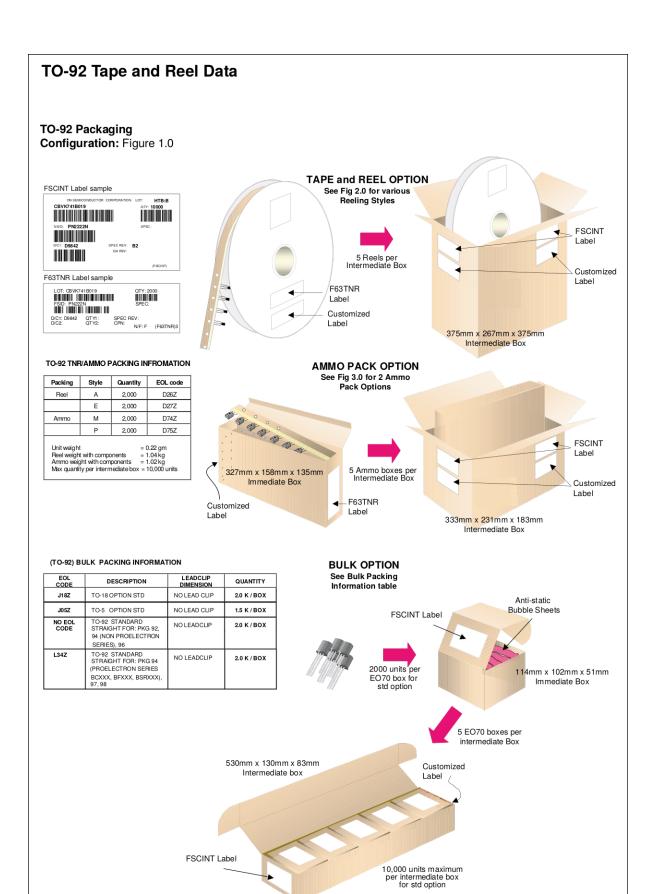








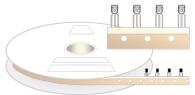




# TO-92 Tape and Reel Data, continued

#### TO-92 Reeling Style Configuration: Figure 2.0

#### Machine Option "A" (H)



Style "A", D26Z, D70Z (s/h)

# Machine Option "E" (J)

Style "E", D27Z, D71Z (s/h)

# **TO-92 Radial Ammo Packaging Configuration:** Figure 3.0

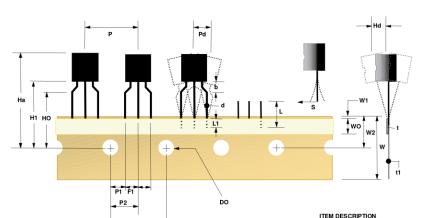




FIRST WIRE OFF IS COLLECTOR (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

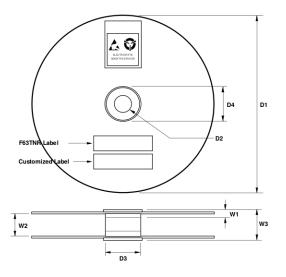
# TO-92 Tape and Reel Data, continued

# **TO-92 Tape and Reel Taping Dimension Configuration:** Figure 4.0



User Direction of Feed

# **TO-92 Reel Configuration:** Figure 5.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	На	0.928 (+/- 0.025)
Lead Clinch Height	НО	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment ( side/side )	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0 .010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note: All dimensions are in inches.

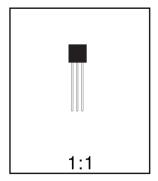
ITEM DESCRIPTION	SYSMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

# **TO-92 Package Dimensions**

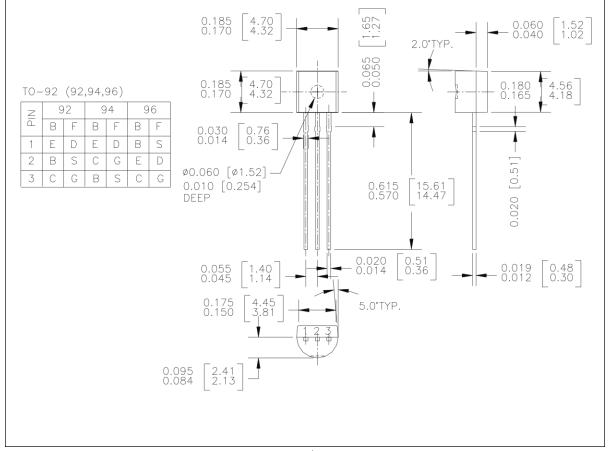
# TO-92 (FS PKG Code 92, 94, 96)

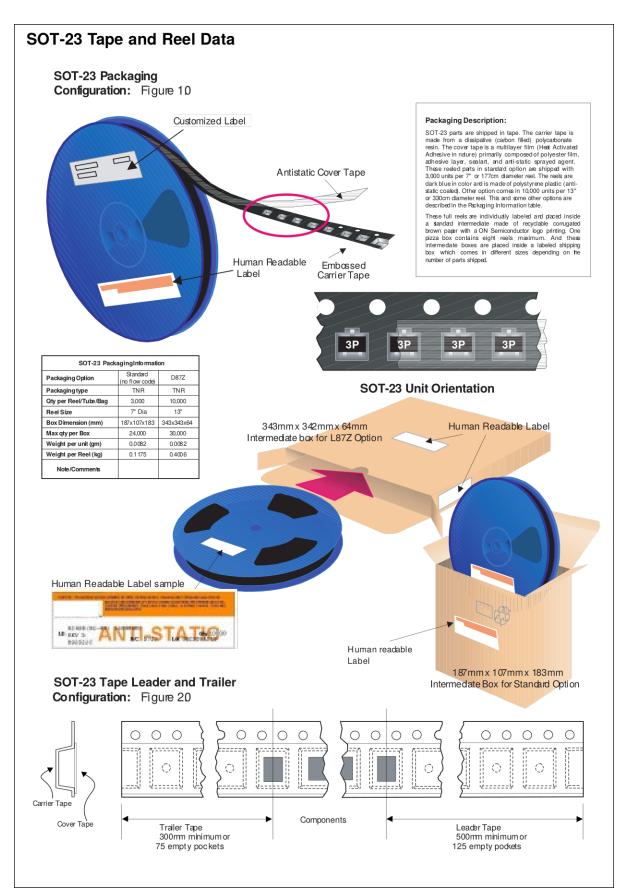




Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

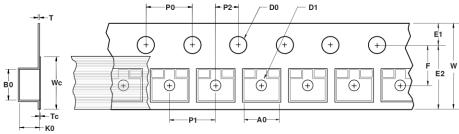




# SOT-23 Tape and Reel Data, continued

# **SOT-23 Embossed Carrier Tape**

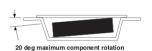
Configuration: Figure 3.0



User Direction of Feed

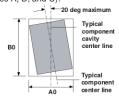
	Dimensions are in millimeter													
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
<b>SOT-23</b> (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)

Component Rotation

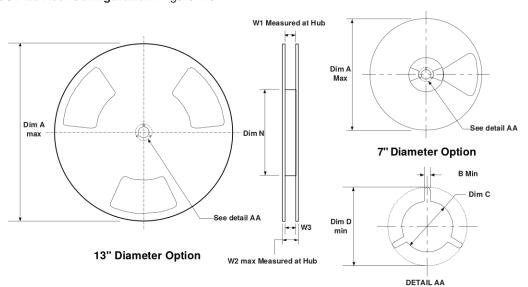


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

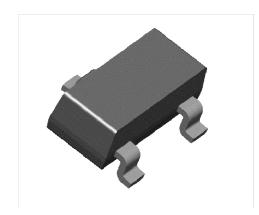
#### SOT-23 Reel Configuration: Figure 4.0

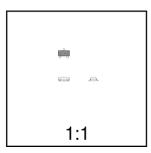


	Dimensions are in inches and millimeters										
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)		
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9		
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9		

# **SOT-23 Package Dimensions**

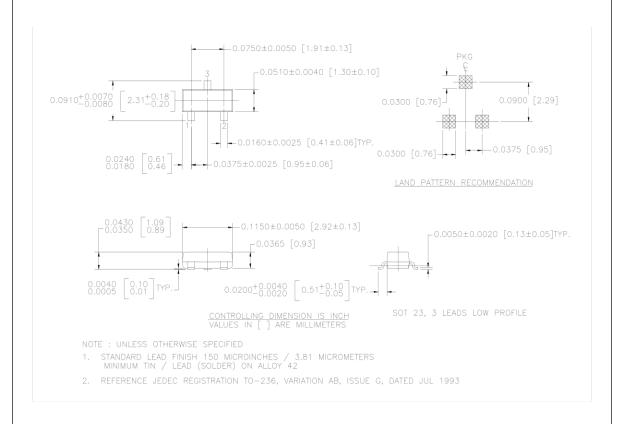
# SOT-23 (FS PKG Code 49)





Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082



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